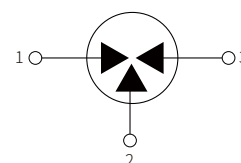


FEATURES

- | Size Design 6.0*6.0*8.0mm
- | High Current Handling Capability 10,000A @ 8/20 μ s
- | Low Capacitance and Insertion Loss
- | Quick Response and Long Service Life
- | Moisture sensitivity level Level 1



6.0*6.0*8.0mm



Schematic Symbol

APPLICATION INFORMATION

- | Communication equipment.
- | Repeaters, Modems
- | Telephone Interface, Line cards.
- | Data communication equipment.

AGENCY APPROVALS

Icon	Solderability
RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003
	Mean lead free
	UL Certificated E505857

PRODUCT CHARACTERISTICS

Lead Material	Body Material	Terminal Finish
Copper or Fe-Ni alloy	Ceramics	100% Matte-Tin Plated

ELECTRICAL PARAMETER

Parameter	Symbol	Rating	Unit
DC Blocking Voltage 1)2)	100V/s	72-108	V
Impulse Spark-over Voltage	At 1kV/μs	for 99 % of measured values ≤800	V
	At 1kV/μs	Typical values of distribution ≤750	V
Impulse Discharge Current 3)	8/20μs	10	KA
Insulation Resistance	DC=50V	≥ 1	GΩ
Capacitance at 1MHz	V _{dc} =0.5V	≤ 1.5	pF
Weight		~1.25	g
Operating and Storage Temperature		-40~125	°C

1) At delivery AQL 0.65 level II SO2859

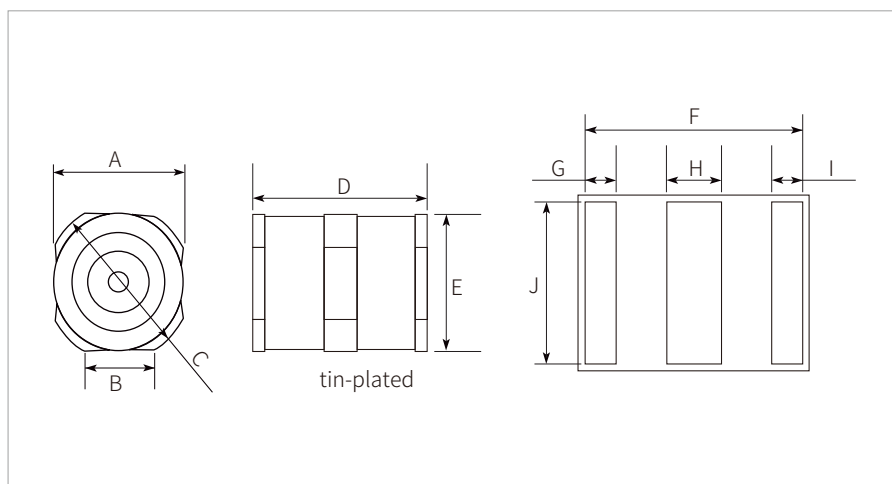
2) In ionized mode

3) Terms and waveforms in accordance with ITU-T Rec. K. 12; IIEC 61643-311

ENVIRONMENTAL RELIABILITY CHARACTERISTICS

Testing items	Technical standards
High Temperature Storage Test	Temperature: 85°C ; Time:2H
Low Temperature Storage Test	Temperature: -40°C ; Time:2H
Vibration	Frequency: 10-500Hz ; Amplitude 0.15mm ; Time:45min
Resistance of soldering heat	Temperature: 260°C; Time of dip soldering 10s,1time

PRODUCT DIMENSIONS



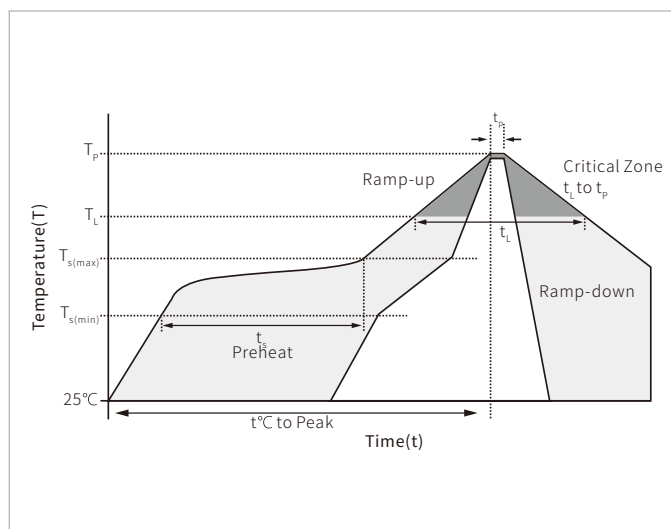
Ref.	Outline Dimensions
	Millimeters
A	6.0±0.2
B	3.2
C	Φ6.8
D	8.2±0.3
E	Φ6.0±0.1
F	8.8
G	1.2
H	2.2
I	1.2
J	6

SOLDERABILITY TEST

Solderability	
Solder Pot Temperature	Solder Dwell Time
245°C ± 5°C	4~6 seconds

REFLOW PROFILE

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Min	150°C
	Temperature Max	200°C
	Time(min to max)	60~180 secs
Average ramp up rate (Liquidus)Temp(T _L) to peak		3°C/second max
T _s (max)to T _L - Ramp-up Rate		
Reflow	Temperature (T _L) (Liquidus)	217°C
	Time(min to max)(t _r)	60~150 seconds
Peak Temperature (T _p)		260 °C
Time within 5°C of actual peak Temperature (t _p)		20~40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T _p)		8 minutes max.
Do not exceed		260°C



ORDERING INFORMATION

Part Number	Size	QTY/Reel	Reel Size
SG3R06B090C	6.0*6.0*8.0mm	600PCS	13 "

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By QR Code

Website



Wechat

To find your local partner within Semiware's global website: www.semiware.com

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